N -Channel Logic Level Enhancement Mode Power MOSFET

MTN3023J3

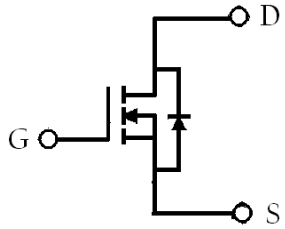
BV_{DSS}		30V
I_D @ V_{GS}=10V, T_C=25°C		30A
$R_{DSON(TYP)}$	V_{GS}=10V, I_D=20A	14mΩ
	V_{GS}=4.5V, I_D=10A	21mΩ

Features

- Low Gate Charge
- Simple Drive Requirement
- Pb-free lead plating and halogen-free package

Equivalent Circuit

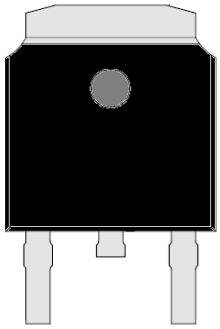
MTN3023J3



G：Gate D：Drain
S：Source

Outline

TO-252(DPAK)



G D S

Ordering Information

Device	Package	Shipping
MTN3023J3-0-T3-G	TO-252 (Pb-free lead plating and halogen-free package)	2500 pcs / Tape & Reel

Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T3 : 2500 pcs / tape & reel, 13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (T_C=25°C, unless otherwise noted)

Parameter		Symbol	Limits	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	
Continuous Drain Current @ V_{GS}=10V, T_C=25°C		I_D	30	A
Continuous Drain Current @ V_{GS}=10V, T_C=100°C			18	
Continuous Drain Current @ V_{GS}=10V, T_A=25°C			9	
Continuous Drain Current @ V_{GS}=10V, T_A=100°C			5.7	
Pulsed Drain Current *1		I_{DM}	100	
Power Dissipation	T_C=25℃	P_D	50	W
	T_C=100℃		20	
	T_A=25℃		2.5	
	T_A=100℃		1.0	
Operating Junction and Storage Temperature Range		Tj, Tstg	-55~+150	°C

Note : *1. Pulse width limited by maximum junction temperature
*2. Duty cycle ≤ 1%

Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-case, max	$R_{th,j-c}$	2.5	°C/W
Thermal Resistance, Junction-to-ambient, max	$R_{th,j-a}$	50 (Note)	

Note : The value of Rth,j-a is measured with the device mounted on 1 in² FR-4 board with 2 oz. copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design.

Electrical Characteristics (Tj=25°C, unless otherwise noted)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV_{DSS}	30	-	-	V	V_{GS}=0V, I_D=250μA
$\Delta BV_{DSS}/\Delta Tj$	-	0.02	-	V/℃	Reference to 25℃, I_D=1mA
$V_{GS(th)}$	1	-	2.5	V	V_{DS}=V_{GS}, I_D=250μA
I_{GSS}	-	-	±100	nA	V_{GS}=±20V, V_{DS}=0V
I_{DSS}	-	-	1	μA	V_{DS}=24V, V_{GS}=0V, Tj=25℃
	-	-	25		V_{DS}=24V, V_{GS}=0V, Tj=70℃
*$R_{DS(ON)}$	-	14	20	mΩ	I_D=20A, V_{GS}=10V
	-	21	28		I_D=10A, V_{GS}=4.5V
*G_{FS}	-	13	-	S	V_{DS}=5V, I_D=15A
Dynamic					
Ciss	-	750	-	pF	V_{DS}=25V, V_{GS}=0V, f=1MHz
Coss	-	61	-		
Crss	-	52	-		

$t_{d(ON)}$	-	10	-	ns	V_{DS}=15V, I_D=1A, V_{GS}=10V, R_G=6Ω, R_D=15Ω
t_r	-	17	-	ns	
$t_{d(OFF)}$	-	36	-	ns	
t_f	-	18	-	ns	
Qg	-	22	-	nC	V_{DS}=15V, I_D=20A, V_{GS}=10V,
Qgs	-	4.2	-	nC	
Qgd	-	3.1	-	nC	

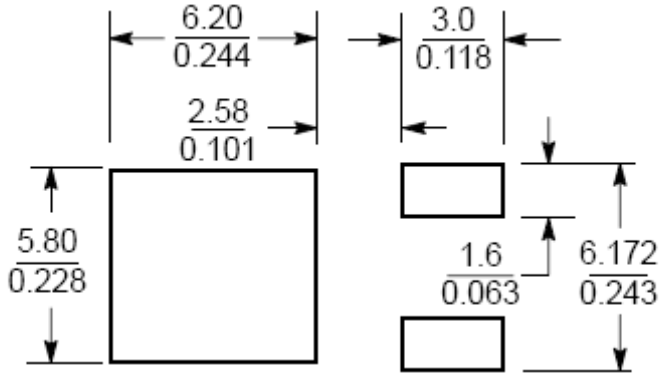
*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

Source Drain Diode

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
*V_{SD}	-	-	1.3	V	I_S=15A,V_{GS}=0V
*T_{rr}	-	10	-	ns	I_S=20A,V_{GS}=0V, dI/dt=100A/μs
Q_{rr}	-	21	-	nC	

*Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

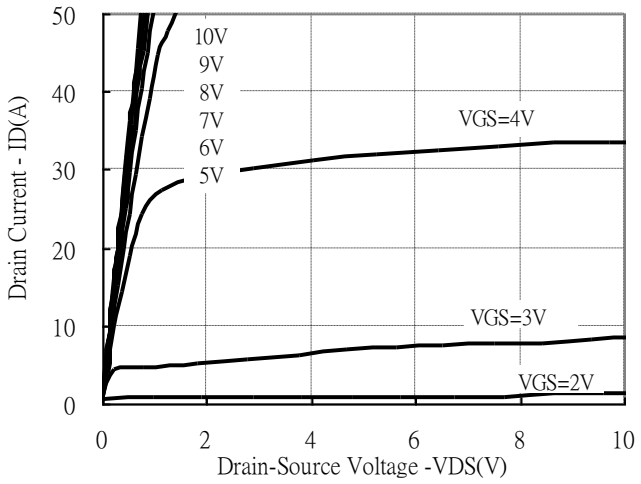
Recommended soldering footprint



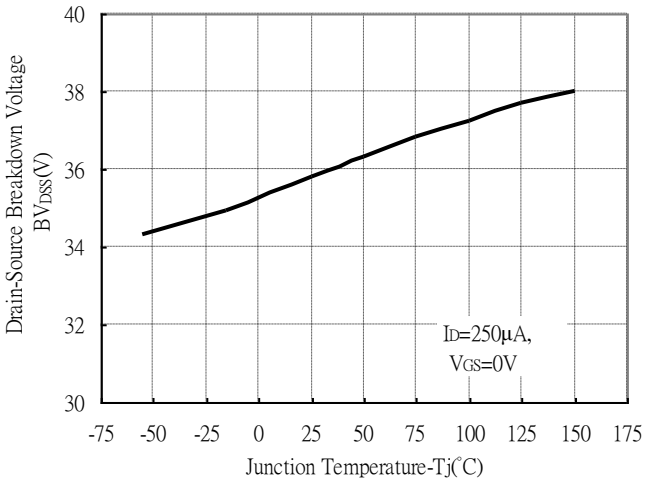
Unit (mm / inch)

Typical Characteristics

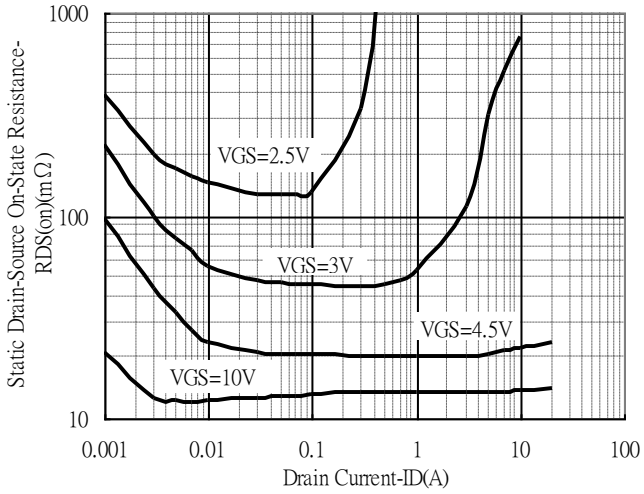
Typical Output Characteristics



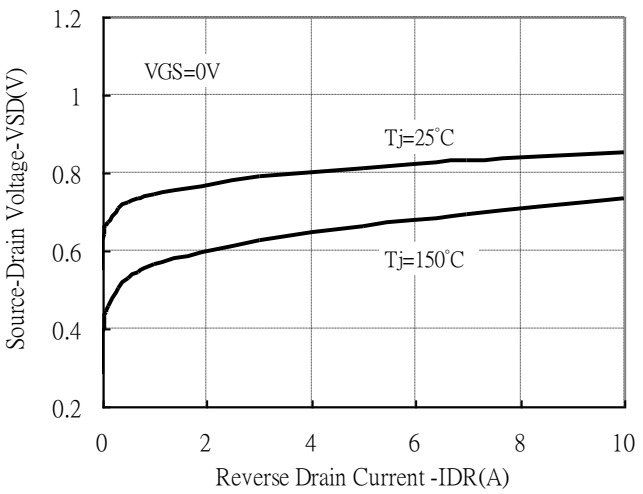
Brekdown Voltage vs Ambient Temperature



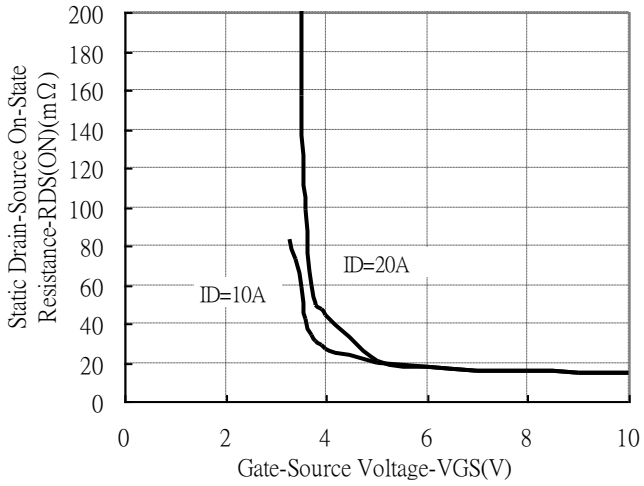
Static Drain-Source On-State resistance vs Drain Current



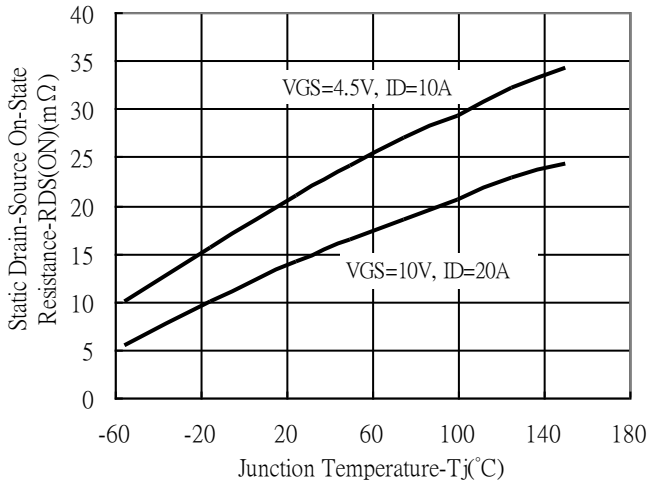
Reverse Drain Current vs Source-Drain Voltage



Static Drain-Source On-State Resistance vs Gate-Source Voltage

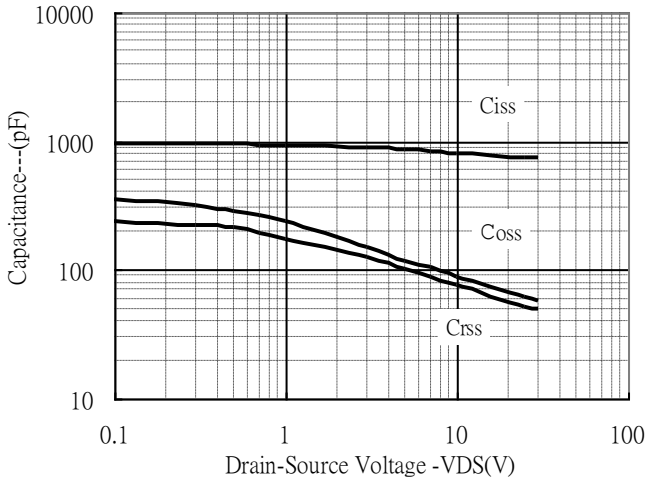


Drain-Source On-State Resistance vs Junction Tempearture

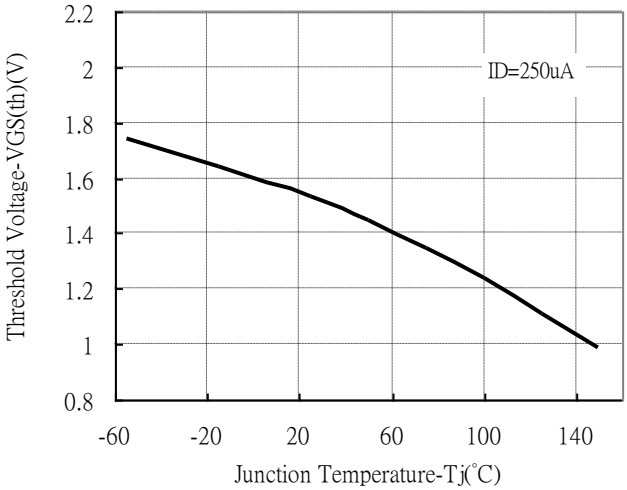


Typical Characteristics(Cont.)

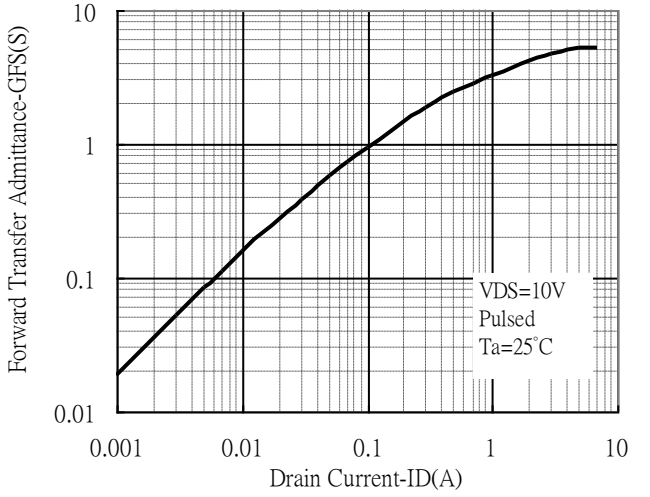
Capacitance vs Drain-to-Source Voltage



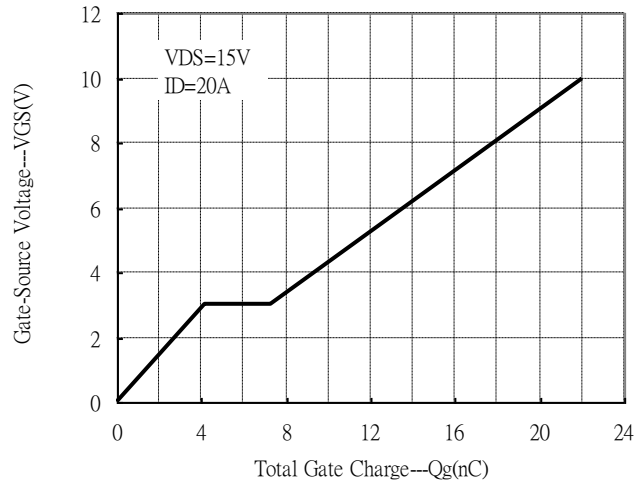
Threshold Voltage vs Junction Tempearture



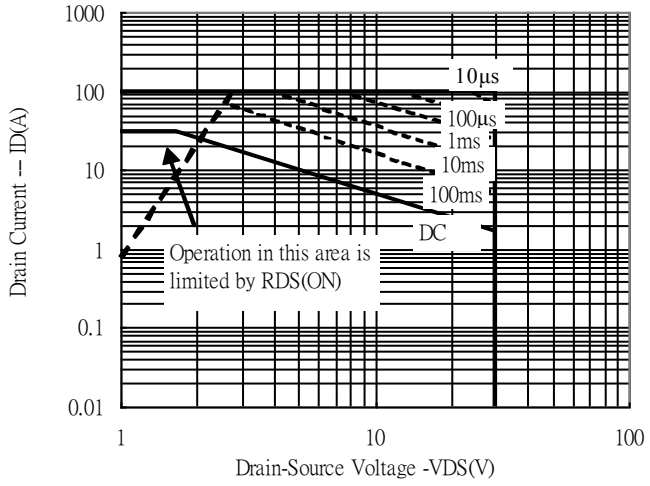
Forward Transfer Admittance vs Drain Current



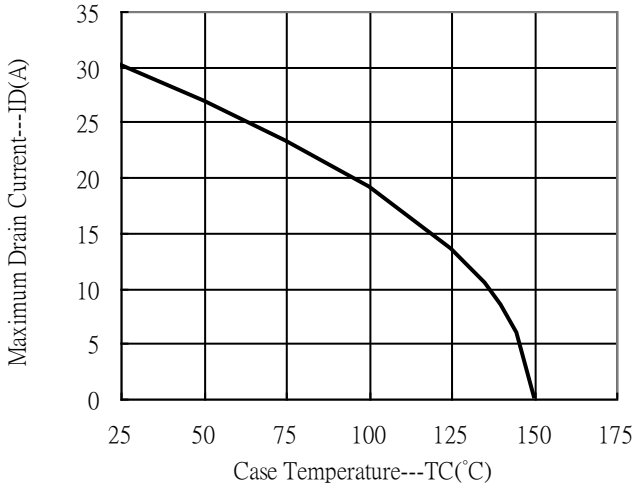
Gate Charge Characteristics



Maximum Safe Operating Area

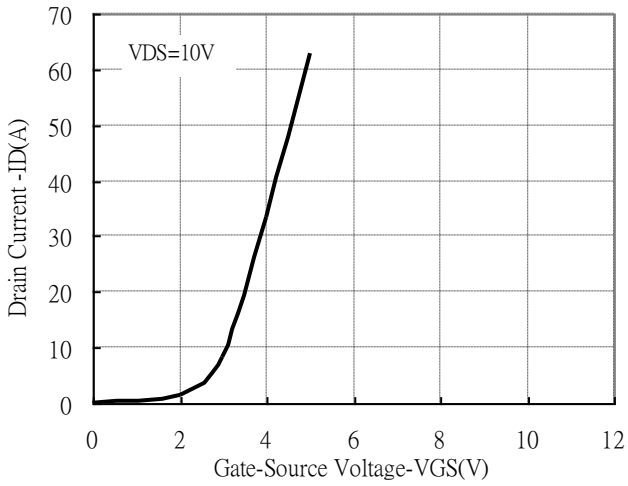


Maximum Drain Current vs Case Temperature

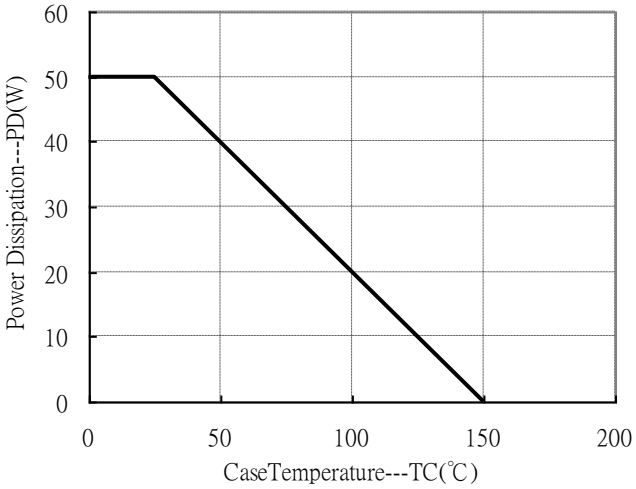


Typical Characteristics(Cont.)

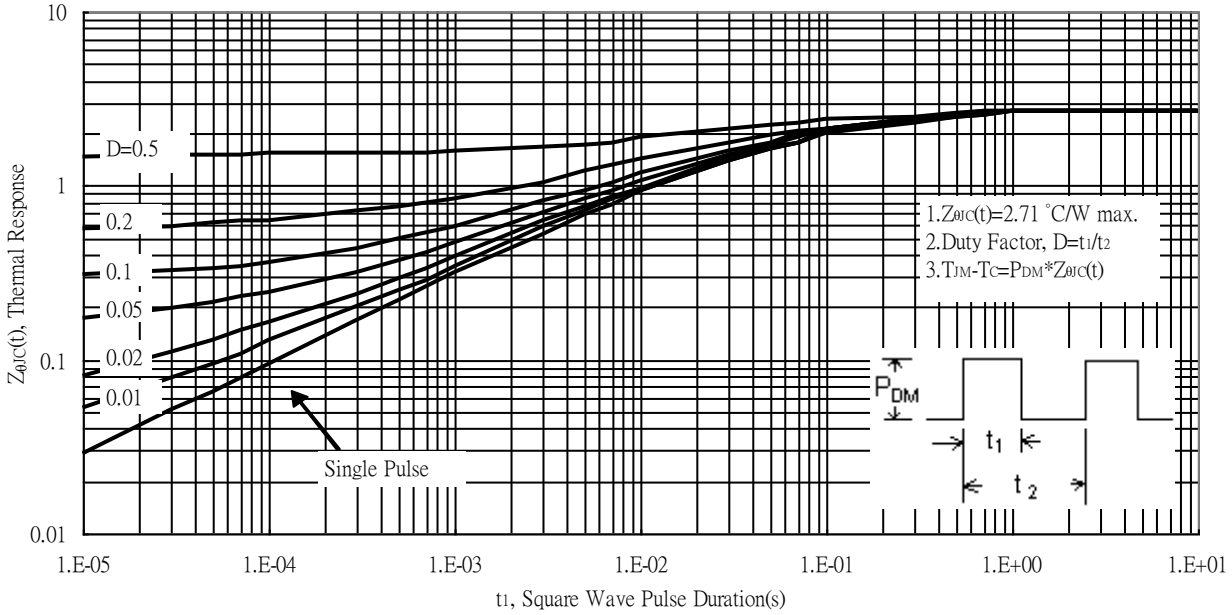
Typical Transfer Characteristics



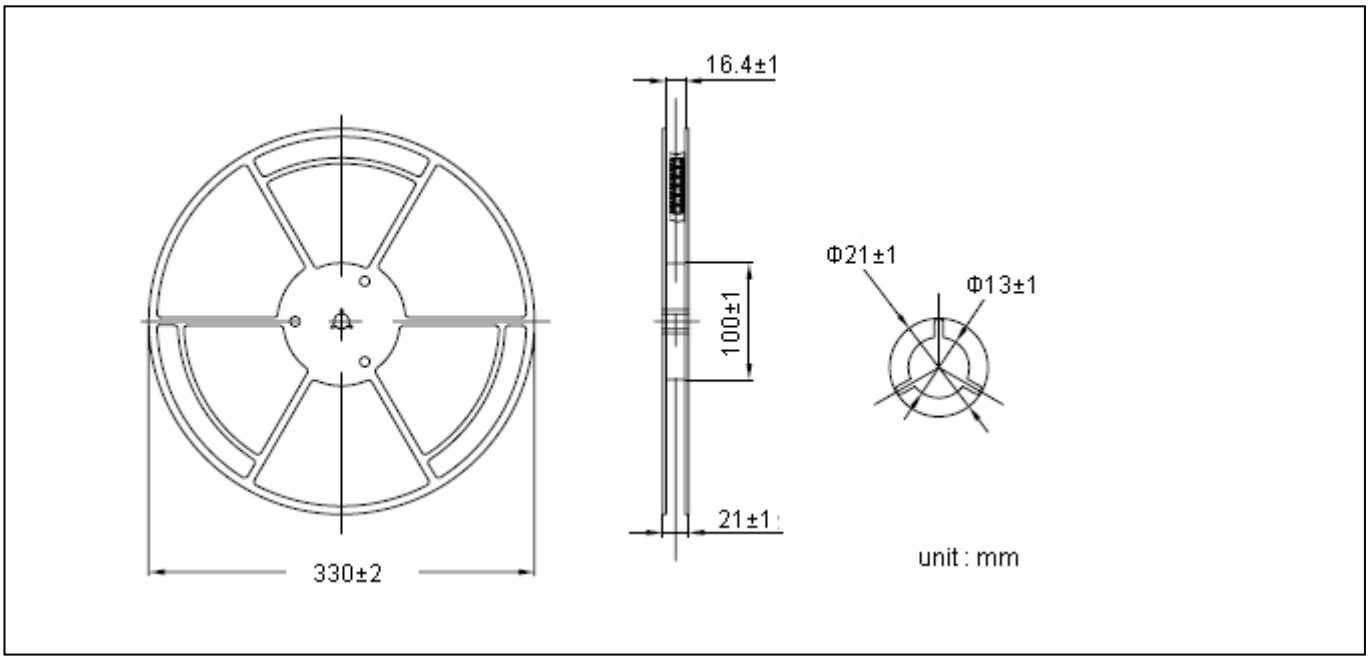
Power Derating Curve



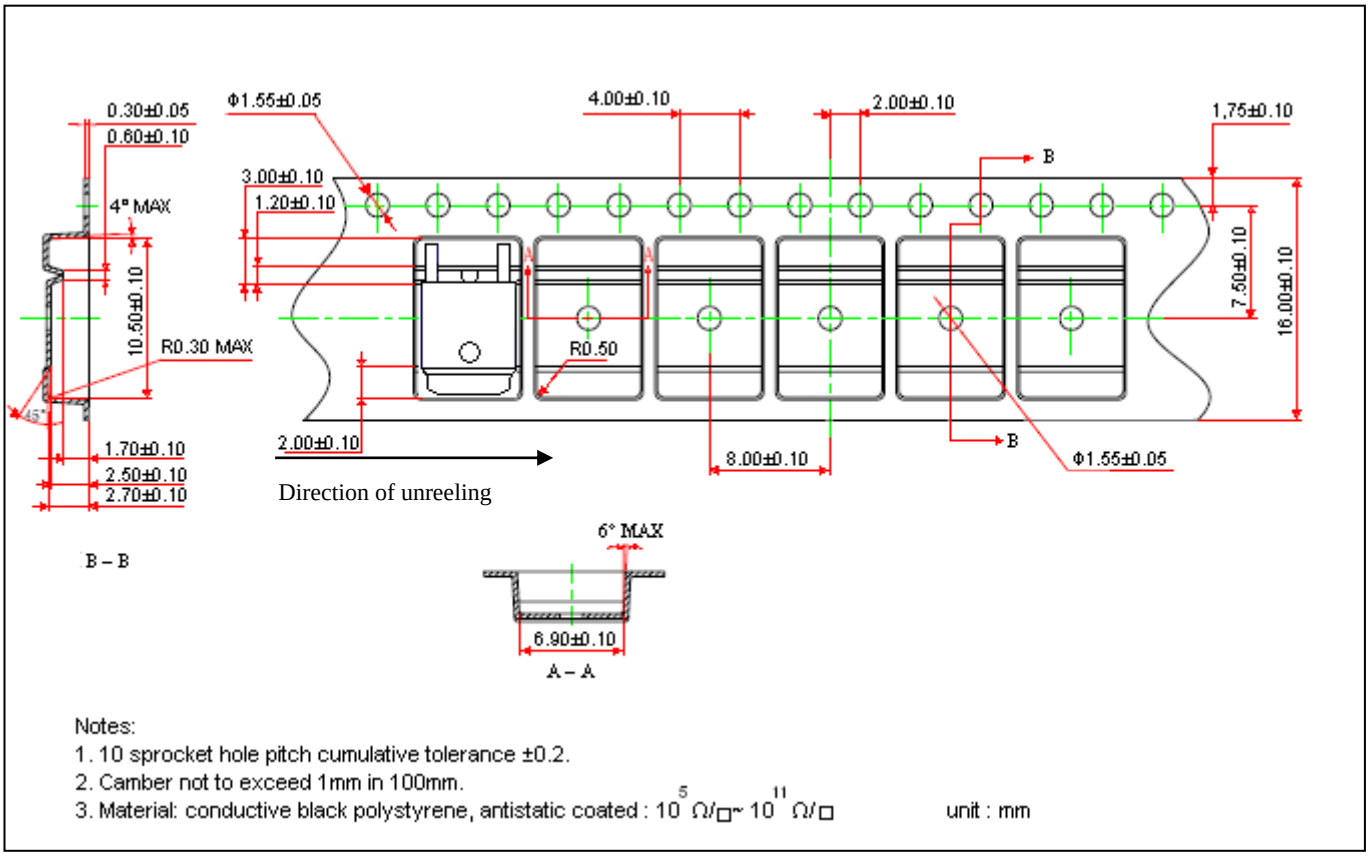
Transient Thermal Response Curves



Reel Dimension



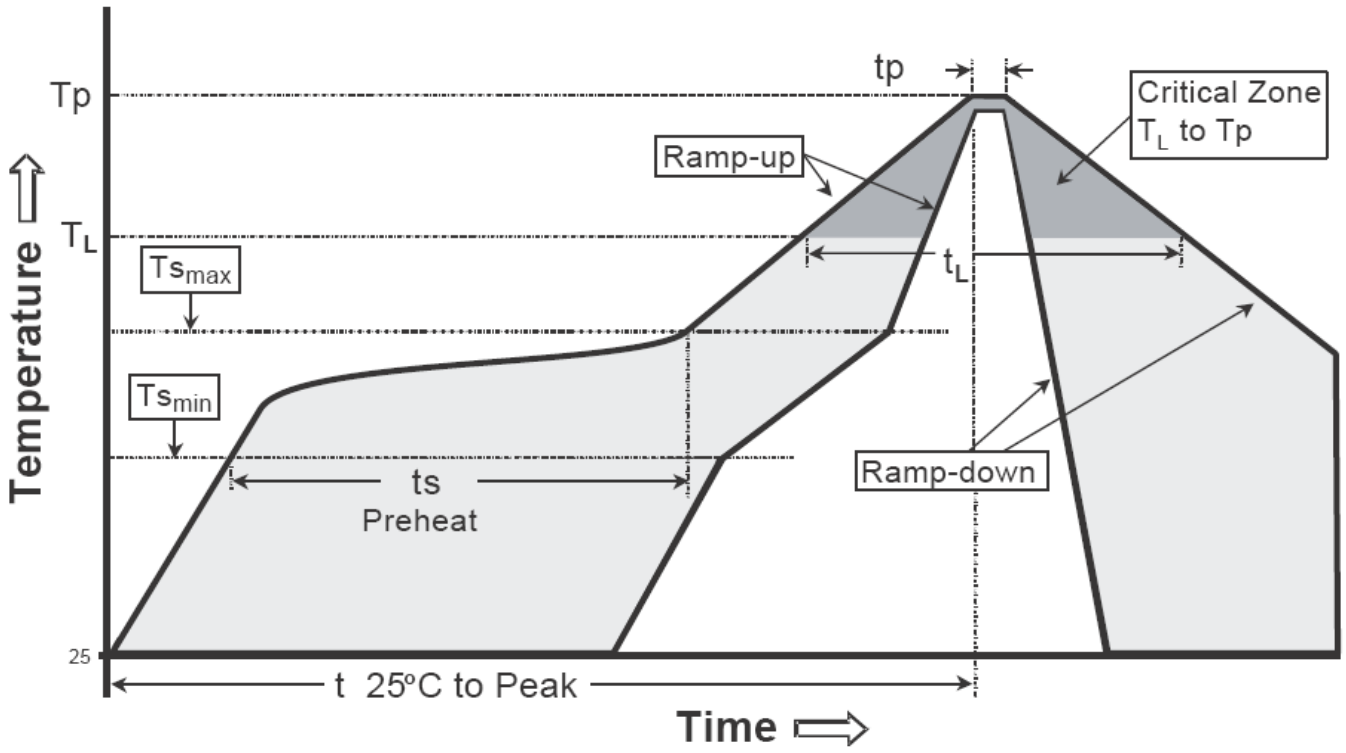
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

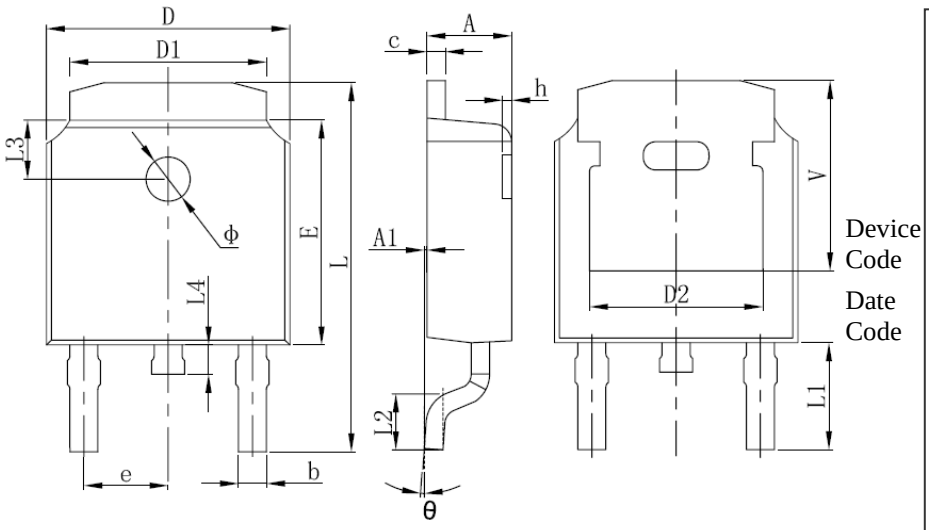
Recommended temperature profile for IR reflow

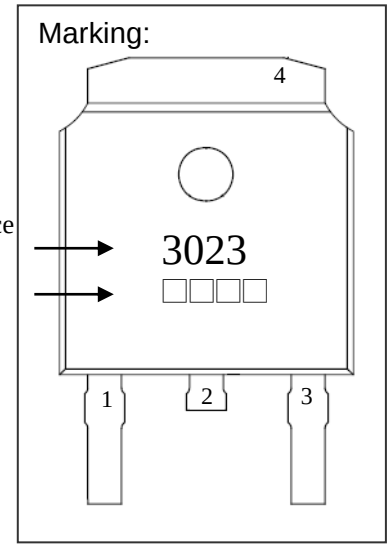


Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time($t_{s\ min}$ to $t_{s\ max}$)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

TO-252 Dimension





3-Lead TO-252 Plastic Surface Mount Package
CYStek Package Code: J3

Style: Pin 1.Gate 2.Drain 3.Source 4.Drain

Date Code :
First Code : Last digit of Christian Year
Second Code : Month Code : Jan→A, Feb→B, Mar→C, Apr→D, May→E, Jun→F, Jul→G, Aug→H, Sep→J, Oct→K, Nov→L, Dec→M
Last Two Codes : Production Serial Code, 01~99

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.087	0.094	2.200	2.400	L	0.382	0.406	9.712	10.312
A1	0.000	0.005	0.000	0.127	L1	0.114 REF		2.900 REF	
b	0.025	0.030	0.635	0.770	L2	0.055	0.067	1.400	1.700
c	0.018	0.023	0.460	0.580	L3	0.063 REF		1.600 REF	
D	0.256	0.264	6.500	6.700	L4	0.024	0.039	0.600	1.000
D1	0.201	0.215	5.100	5.460	Φ	0.043	0.051	1.100	1.300
D2	0.190 REF		4.830 REF		θ	0°	8°	0°	8°
E	0.236	0.244	6.000	6.200	h	0.000	0.012	0.000	0.300
e	0.086	0.094	2.186	2.386	v	0.207 REF		5.250 REF	

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead : Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.